

**DESCRIPTION**

The AM30N06 is available in TO-252 Package.

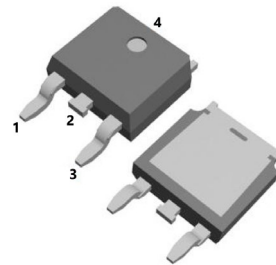
BVDSS	RDSON	ID
60V	24mΩ	30A

**ORDERING INFORMATION**

Package Type	Part Number	
TO-252 SPQ: 2,500pcs/Reel	D	AM30N06DVR
Note	R: Tape & Reel V: Halogen free Package	
AiT provides all RoHS products		

**FEATURE**

- Super Low Gate Charge
- Excellent  $C_{dv}/dt$  effect decline

**PIN DESCRIPTION**

TO-252

Pin #	Symbol	Function
1	G	Gate
2,4	D	Drain
3	S	Source

**ABSOLUTE MAXIMUM RATINGS**

$T_C = 25^\circ\text{C}$ , unless otherwise specified.

$V_{DSS}$ , Drain-Source Voltage		60V
$V_{GSS}$ , Gate-Source Voltage		$\pm 30\text{V}$
$I_D$ , Continuous Drain Current	$T_C = 25^\circ\text{C}$	30A
	$T_C = 100^\circ\text{C}$	13A
$I_{DM}$ , Pulsed Drain Current <sup>(1)</sup>		100A
$E_{AS}$ , Single Pulse Avalanche Energy <sup>(2)</sup>		39mJ
$P_D$ , Power Dissipation	$T_C = 25^\circ\text{C}$	41.70W
$R_{\theta JC}$ , Thermal Resistance, Junction to Case		50°C/W
$T_{STG}$ , Storage Temperature Range		-55°C ~ +175°C
$T_J$ , Operating Junction Temperature Range		-55°C ~ +175°C

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

(1) Repetitive Rating: pulse width limited by maximum junction temperature  $T_{J(MAX)}=150^\circ\text{C}$ .

(2) The EAS data shows Max. rating. The test condition is  $V_{DD}=25\text{V}$ ,  $V_{GS}=10\text{V}$ ,  $L=0.4\text{mH}$ ,  $I_{AS}=14\text{A}$

**ELECTRICAL CHARACTERISTICS**T<sub>J</sub> = 25°C, unless otherwise specified.

Parameter	Symbol	Conditions	Min	Typ.	Max	Unit	
<b>Static Characteristics</b>							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	60	-	-	V	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =±20V, V <sub>GS</sub> =0V	-	-	±100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> =60V, V <sub>DS</sub> =0V	T <sub>J</sub> = 25°C	-	-	1	μA
			T <sub>J</sub> = 100°C	-	-	100	
Gate-Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.2	1.7	2.5	V	
Drain-Source On-Resistance <sup>(1)</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A	-	24	32	mΩ	
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 5A	-	31.5	40		
Forward Transconductance <sup>(1)</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 10A	-	15.5	-	S	
<b>Dynamic Characteristics <sup>(2)</sup></b>							
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, f=1.0MHZ	-	1355	-	pF	
Output Capacitance	C <sub>oss</sub>		-	60	-		
Reverse Transfer Capacitance	C <sub>rss</sub>		-	49	-		
Gate Resistance	R <sub>G</sub>	f=1.0MHZ	-	1.2	-	Ω	
<b>Switching Characteristics <sup>(2)</sup></b>							
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30V, R <sub>G</sub> =3Ω, V <sub>GS</sub> =10V, I <sub>D</sub> = 10A	-	6.4	-	ns	
Turn-On Rise Time	t <sub>r</sub>		-	15.3	-		
Turn-Off Delay Time	t <sub>d(off)</sub>		-	25	-		
Turn-Off Fall Time	t <sub>f</sub>		-	7.6	-		
Total Gate Charge	Q <sub>g</sub>	V <sub>DD</sub> = 30V , I <sub>D</sub> = 10V V <sub>GS</sub> =10V	-	22	-	nC	
Gate-Source Charge	Q <sub>gs</sub>		-	4.2	-		
Gate-Drain Charge	Q <sub>gd</sub>		-	6.9	-		
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =10A, dI <sub>F</sub> /dt=100A/μs	-	26	-	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>		-	45	-	nC	
<b>Drain-Source Body Diode Characteristics</b>							
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =20A, V <sub>GS</sub> =0V	-	-	1.2	V	
Continuous Source Current	I <sub>S</sub>		-	-	30	A	

(1) Pulse text: Pulse width ≤ 300μs, Duty Cycle ≤ 2%.

(2) This value is guaranteed by design hence it is not included in the production test.



## TYPICAL PERFORMANCE CHARACTERISTICS

Fig 1. Output Characteristics

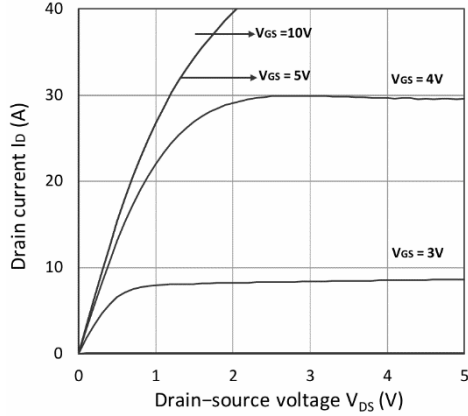


Fig 2. Transfer Characteristics

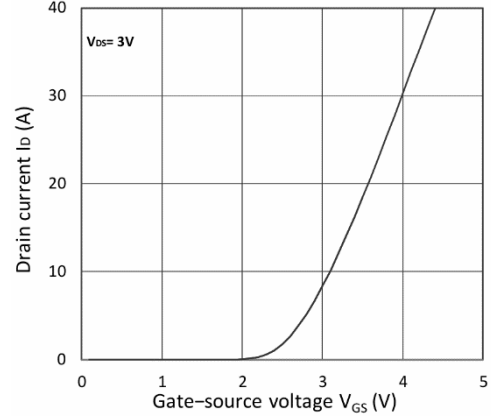


Fig 3. Forward Characteristics of Reverse

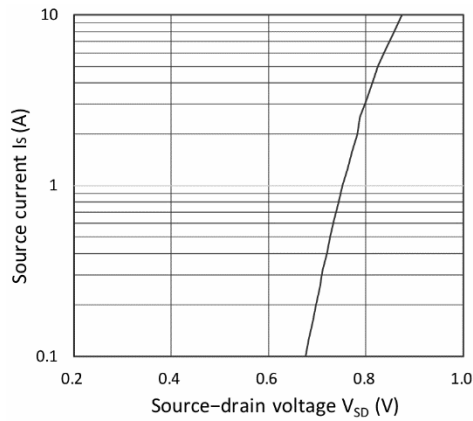


Fig 4.  $R_{DS(ON)}$  vs.  $V_{GS}$

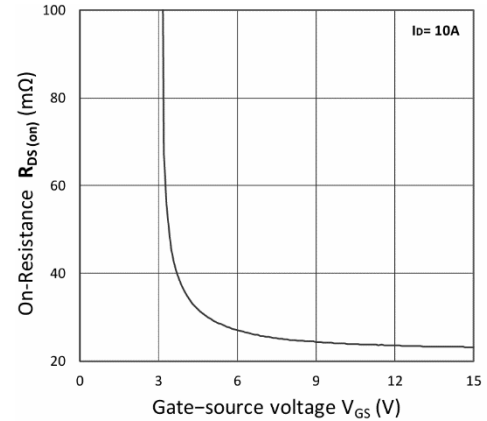


Fig 5.  $R_{DS(ON)}$  vs.  $I_D$

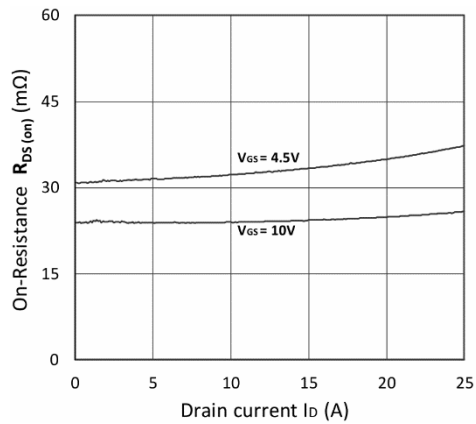


Fig 6. Normalized  $R_{DS(on)}$  vs. Temperature

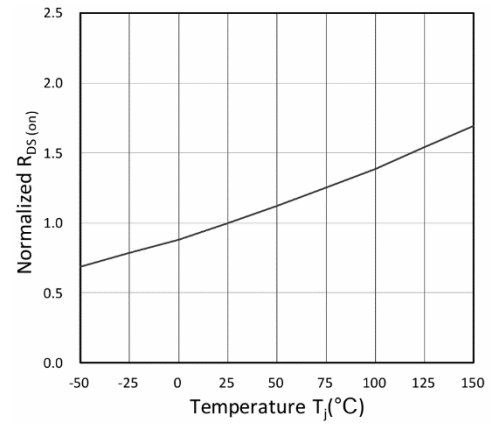




Fig 7. Capacitance Characteristics

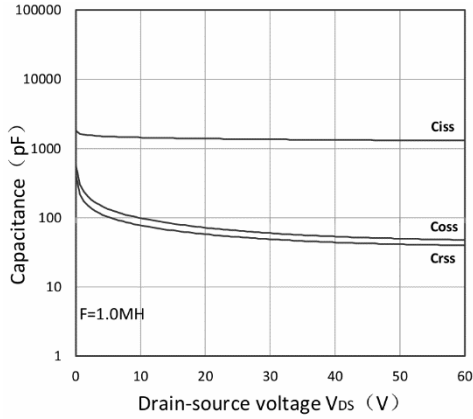


Fig 8. Gate Charge Characteristics

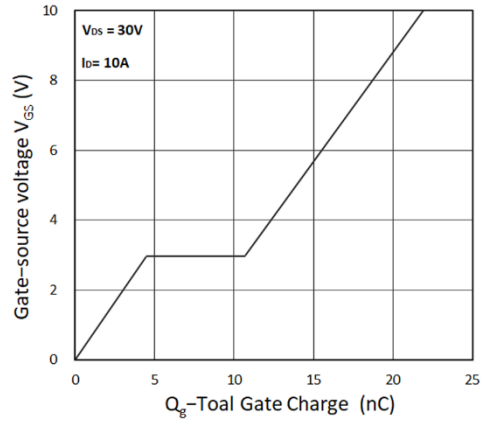


Fig 9. Power Dissipation

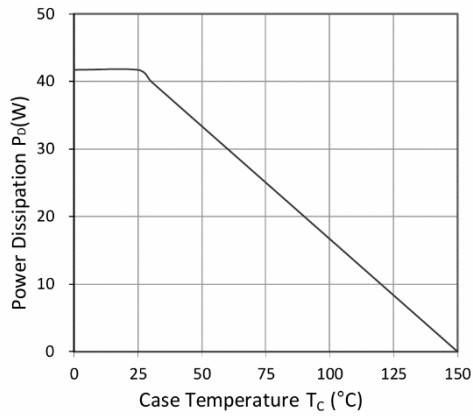


Fig 10. Safe Operating Area

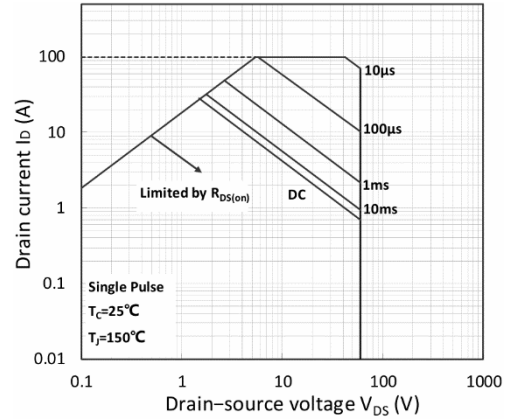
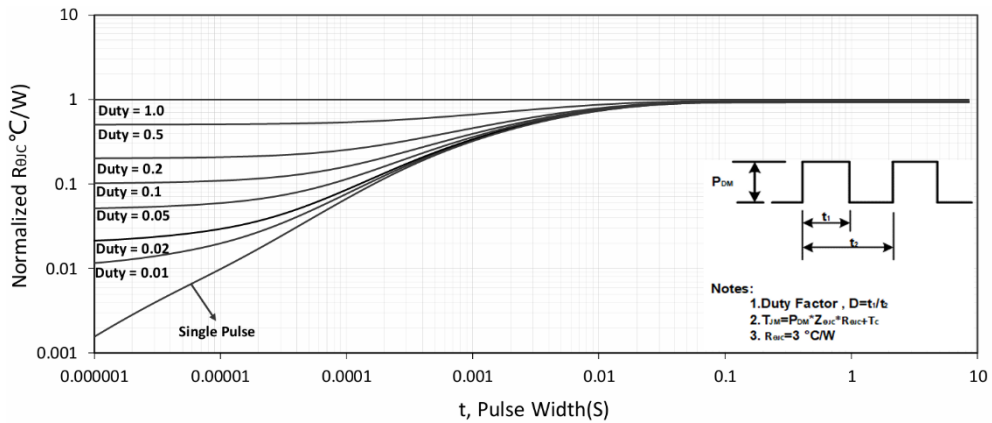


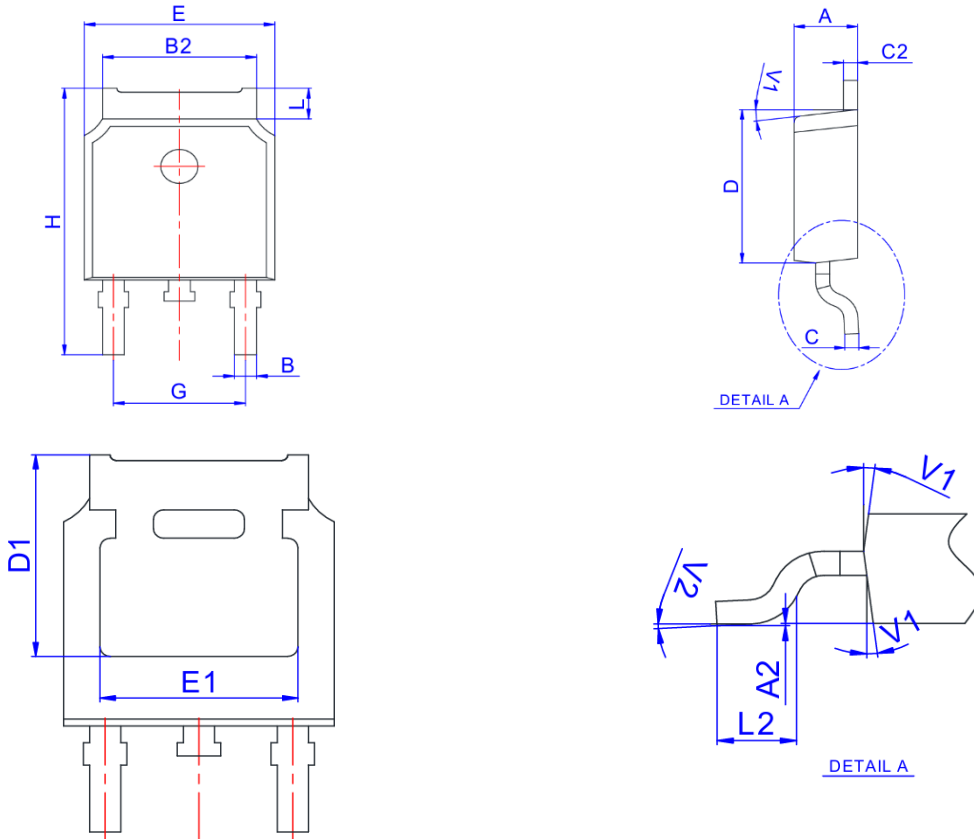
Fig 11. Normalized Maximum Transient Thermal Impedance





**PACKAGE INFORMATION**

Dimension in TO-252 (Unit: mm)



Symbol	Millimeters (mm)	
	Min.	Max.
A	2.100	2.500
A2	0.000	0.100
B	0.660	0.860
B2	5.180	5.480
C	0.400	0.600
C2	0.440	0.580
D	5.900	6.300
D1	5.300 REF.	
E	6.400	6.800
E1	4.630	-
G	4.470	4.670
H	9.500	10.700
L	1.090	1.210
L2	1.350	1.650
V1	7°	
V2	0°	6°



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